

AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning at page 3, line 23 for the following amended paragraph:

These measures exert effect for preventing gelation due to a network structure in polyamide, but a finer filter is being used on molding a resin for purposes requiring increased precision in recent years, which brings about such a problem that a filter is often clogged, and thus is necessarily exchanged frequently.

Patent Document	1:	JP-A-49-45960
Patent Document	2:	JP-A-49-53945
Patent Document	3:	JP-[[A]]B-45-11836
Patent Document	4:	JP-[[A]]B-45-35667
Patent Document	5:	JP-[[A]]B-45-12986
Patent Document	6:	JP-[[A]]B-46-38351
Patent Document	7:	JP-A-2001--164109

Please replace the subtitle on page 5, line 5, for the following amended subtitle.

MEANS FOR SOLVING THE ~~INVENTION~~ PROBLEMS

Please replace the paragraph beginning at page 19, line 1, with the following amended paragraph:

Examples of a sodium metallic compound capable of being used in the polyamide resin composition of the invention include sodium hydroxide, sodium acetate, ~~sodium acetate~~, sodium

methoxide, sodium ethoxide, sodium propoxide, sodium butoxide and sodium carbonate, and among these, sodium hydroxide and sodium acetate are preferably used, but the invention is not limited to these compounds.

Please replace the paragraph [0042] on page 20 with the following amended paragraph:

[0042]

The upper limit of the Co-b value in the embodiment A is preferably 5, more preferably 4, further preferably 3, and particularly preferably 2. In the case where the Co-b value is too high, yellowing occurring on a post-process of a bottle, a film, fibers or the like is outstanding, which may brings about deterioration in quality of products. In the case where the Co-b value is decreased excessively, the addition amount of a stabilizer, such as a phosphorous atom-containing compound, may be too large, whereby it is disadvantageous in cost, and filter clogging may occur due to the additive. In order to make the Co-b value within the aforementioned range, the addition amounts of the phosphorous atom-containing compound and the sodium metallic compound may be optimized, and furthermore such measures may be employed that the upper limit of the temperature on reaction is 270°C or less, preferably 265°C or less, and more preferably 260°C or less, and the oxygen concentration on reaction is preferably 200 ppm or less, more preferably 150 ppm or less, and further preferably 100 ppm or less.

Please replace the paragraph [0052] on page 26, with the following amended paragraph:

[0052]

The lower limit of the back pressure increasing coefficient K^* is preferably lowered to such a value that is equal to K^* when no additive is mixed even in ~~this case~~ the case where a

continuous production for a considerably long period of time is carried out, and the K^* value with no additive may be practically considered as one reference of the lower limit. The lower limit of K^* is not particularly limited, and is 1 in one embodiment, 1.5 in another embodiment, 2 in still another embodiment, and 2.5 in a further embodiment.

Please replace the paragraph [0078] on page 55, with the following amended paragraph:

[0078]

EXAMPLE B-8

The polymerization method of polyamide was carried out in the same manner as in Example B-1 except that 0.53 g of H_3PO_2 and 1.5 g of $LiOH \cdot H_2O$ as additives were added. The resulting resin had a relative viscosity (RV) of 2.15 and a Co-b value of 9.2. The resulting resin was dried in a 100 L blender at an inner temperature of 120°C for 12 hours, further subjected to solid phase polymerization at an inner temperature of 180°C, and then cooled to obtain chips. The RV was 2.67, the Co-b value was 9.4, and the water content was 200 ppm, in this stage. The residual amounts of phosphorous atoms, ~~[[and]]~~ sodium atoms and lithium atoms were $P = 5$ ppm, $Na = 0.1$ ppm and $Li = 5$ ppm, respectively. The polyamide resin composition was fused by using a uniaxial extruder and extruded in a given amount at a rate of 3 g/min by using a gear pump. Foreign matters in the polymer were filtered with a filter having a filtering diameter of 20 μm , and the pressure on the secondary side of the gear pump was recorded with lapse of time. The back pressure increasing coefficient K^* after extruding for 4 hours was 2.2. Observation of the filter revealed that no clogging was found. Observation of the heat deterioration state of the resulting extrusion molded article revealed that no gelled product due to heat deterioration was observed.

Please replace the paragraph [0079] on page 56, for the following amended paragraph:

[0079]

EXAMPLE B-9

The polymerization method of polyamide was carried out in the same manner as in Example B-1 except that 0.53 g of H_3PO_2 and 0.8 g of KOH as additives were added. The resulting resin had a relative viscosity (RV) of 2.10 and a Co-b value of 8.9. The resulting resin was dried in a 100 L blender at an inner temperature of 120°C for 12 hours, further subjected to solid phase polymerization at an inner temperature of 180°C, and then cooled to obtain chips. The RV was 2.62, the Co-b value was 9.2, and the water content was 200 ppm, in this stage. The residual amounts of phosphorous atoms, [[and]] sodium atoms and potassium atoms were P = 5 ppm, Na = 0.1 ppm and K = 5 ppm, respectively. The polyamide resin composition was fused by using a uniaxial extruder and extruded in a given amount at a rate of 3 g/min by using a gear pump. Foreign matters in the polymer were filtered with a filter having a filtering diameter of 20 μm , and the pressure on the secondary side of the gear pump was recorded with lapse of time. The back pressure increasing coefficient K^* after extruding for 4 hours was 3.8. Observation of the filter revealed that no clogging was found. Observation of the heat deterioration state of the resulting extrusion molded article revealed that no gelled product due to heat deterioration was observed.

Please replace the paragraph [0081] on page 58, with the following amended paragraph:

[0081]

REFERENCE EXAMPLE 2

The polymerization method of polyamide was carried out in the same manner as in Example [[1]] B-1 except that 5.1 g of $\text{NaH}_2\text{PO}_2 \cdot \text{H}_2\text{O}$ and 4.0 g of CH_3COONa as additives were added. The resulting resin had a relative viscosity (RV) of 2.15 and a Co-b value of 3.4. The resulting resin was dried in a 100 L blender at an inner temperature of 120°C for 12 hours, further subjected to solid phase polymerization at an inner temperature of 180°C, and then cooled to obtain chips. The RV was 2.65, the Co-b value was 3.8, and the water content was 200 ppm, in this stage. The residual amounts of phosphorous atoms and sodium atoms were P = 30 ppm and Na - 45 ppm, respectively. The polyamide resin composition was fused by using a uniaxial extruder and extruded in a given amount at a rate of 3 g/min by using a gear pump. Foreign matters in the polymer were filtered with a filter having a filtering diameter of 20 μm , and the pressure of the secondary side of the gear pump was recorded with lapse of time. The back pressure increasing coefficient K^* after extruding for 4 hours was 6.0. Observation of the filter revealed that slight clogging was found but was in a level causing no practical problem. Observation of the heat deterioration state of the resulting extrusion molded article revealed that no gelled product due to heat deterioration was observed.